



Product Change Notification: CENO-30XJOJ552

Date:

10-Jul-2026

Product Category:

Crypto Authentication, Crypto Memory, Memory

Notification Subject:

CCB 8379 Final Notice: Implement new packing materials and packing changes for AT34C02D, AT24C08D, AT24HC02C, AT88SC0104CA, AT88SC1616C, AT88SC0404CA, AT24MAC602, ATSHA204A, ATECC608A, ATECC508A, AT93C66B, ATECC108A, ATECC608C, AT24C16C, AT88SC0808CA, AT25160B, AT25080B, 25CS160, 24LC64, AT24C01C, AT24C04C, AT24C128C, AT24C04D, 24AA16H, AT24C08C, 24AA02H, 24LC04B, 24LC16B, AT93C56B, 24AA04H, 24AA01H, 24LC04BH, 24LC02BH, 24LC01BH, 25AA640A, 25LC640A, AT93C46E, 25CS640, AT24CM01, AT24C256C, 24AA256, AT24C512C, 24AA512, 24LC512, AT24C02C, AT25320B, 24LC256, 24FC256, 24FC512, AT24CM02, AT24C64B, AT24HC04B, AT24MAC402, AT24C16D, 25CSM04, AT93C86A, AT93C46D, AT24C02D and AT24C64D device families available in 8L SOIC and TSSOP (3.90mm and 4.4mm) packages.

Affected CPNs:

[CENO-30XJOJ552_Affected_CPN_07102026.pdf](#)

[CENO-30XJOJ552_Affected_CPN_07102026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Implement new packing materials and packing changes for AT34C02D, AT24C08D, AT24HC02C, AT88SC0104CA, AT88SC1616C, AT88SC0404CA, AT24MAC602, ATSHA204A, ATECC608A, ATECC508A, AT93C66B, ATECC108A, ATECC608C, AT24C16C, AT88SC0808CA, AT25160B, AT25080B, 25CS160, 24LC64, AT24C01C, AT24C04C, AT24C128C, AT24C04D, 24AA16H, AT24C08C, 24AA02H, 24LC04B, 24LC16B, AT93C56B, 24AA04H, 24AA01H, 24LC04BH, 24LC02BH, 24LC01BH, 25AA640A, 25LC640A, AT93C46E, 25CS640, AT24CM01, AT24C256C, 24AA256, AT24C512C, 24AA512, 24LC512, AT24C02C, AT25320B, 24LC256, 24FC256, 24FC512, AT24CM02, AT24C64B, AT24HC04B, AT24MAC402, AT24C16D,

25CSM04, AT93C86A, AT93C46D, AT24C02D and AT24C64D device families available in 8L SOIC and TSSOP (3.90mm and 4.4mm) packages.

Pre and Post Summary Changes:

		Pre Change	Post Change	Change (Yes/No)
Final Test Site		ATX Semiconductor (Shanghai) Co. Ltd (ASSH)	ATX Semiconductor (Shanghai) Co. Ltd (ASSH)	No
Tube	Packing Material/Method	Static Shielding Bag without vacuum seal	Moisture Barrier Bag with vacuum seal	Yes
		See Pre and Post Change Summary attachment for comparison		

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by implementing new packing materials and packing changes.

Change Implementation Status: In Progress

Estimated First Ship Date: 17 July 2026 (date code: 2629)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	July 2026				
Work Week	27	28	29	30	31
Qual Report Availability		x			
Final PCN Issue Date		x			
Estimated Implementation Date			x		

Method to Identify Change: Traceability Code, Packing Material

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

July 10, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_CENO-30XJOJ552 Qual Report.pdf

PCN_CENO-30XJOJ552 Pre and Post Change Summary.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.